Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-7 (Canceled)

Claim 8 (Currently amended): A method for manufacturing semiconductor devices, comprising:

placing a lead frame having a semiconductor element mounted thereon, between a top-half mold and a bottom-half mold; and

reducing [[a]] an air pressure in a cavity formed by the top-half mold and the bottom-half mold when a specified amount of resin has been supplied into the cavity.

Claim 9 (Previously presented): The method for manufacturing semiconductor devices of claim 8, wherein the specified amount of resin is an amount of resin that fills about one half of the cavity.

Claim 10 (Previously presented): The method for manufacturing semiconductor devices of claim 8, further comprising:

forcing the resin into the cavity using a plunger; and

detecting a position of the plunger to determine when the specified amount of resin has been supplied to the cavity.

Claim 11 (Previously presented): The method for manufacturing semiconductor devices of claim 8, further comprising:

forcing the resin into the cavity using a plunger; and

detecting an amount of time the plunger is driven to determine when the specified amount of resin has been supplied to the cavity.

Claim 12 (Previously presented): The method for manufacturing semiconductor devices of claim 8, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.

Claims 13-21 (Canceled)

Claim 22 (New): A method of manufacturing a semiconductor device, comprising:

placing a lead frame having a semiconductor element mounted thereon, between a top-half mold and a bottom-half mold;

introducing resin into a cavity formed by the top-half mold and the bottom-half mold; and

reducing a pressure in the cavity by extracting air from the cavity when a

specified amount of resin has been supplied to the cavity.

Claim 23 (New): The method of manufacturing a semiconductor device of claim 22, wherein the specified amount of resin is an amount of resin that fills about one half of the cavity.

Claim 24 (New): The method of manufacturing a semiconductor device of claim 22, wherein said introducing resin comprises forcing the resin into the cavity using a plunger,

the method further comprising detecting a position of the plunger to determine when the specified amount of resin has been supplied to the cavity.

Claim 25 (New): The method of manufacturing a semiconductor device of claim 22, wherein said introducing resin comprises forcing the resin into the cavity using a plunger,

the method further comprising detecting an amount of time the plunger is driven to determine when the specified amount of resin has been supplied to the cavity.

Claim 26 (New): The method of manufacturing a semiconductor device of claim 22, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.

Claim 27 (New): A method of manufacturing a semiconductor device, comprising:

placing a lead frame having a semiconductor element mounted thereon, between a top-half mold and a bottom-half mold;

introducing resin into a cavity formed by the top-half mold and the bottom-half mold using a plunger; and

reducing a pressure in the cavity by extracting air from the cavity according to an amount of time the plunger is driven.

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Claim 28 (New): The method of manufacturing a semiconductor device of claim 27, wherein said reducing a pressure in the cavity begins once the plunger is driven an amount of time necessary to introduce an amount of resin that fills about one half of the cavity.

Claim 29 (New): The method of manufacturing a semiconductor device of claim 27, wherein said reducing a pressure in the cavity begins once the plunger is driven an amount of time necessary for the resin that is introduced into the cavity to begin hardening.

Claim 30 (New): A method of manufacturing semiconductor device packages comprising:

providing a transfer molding apparatus including a top-half mold and a bottom-

half mold that forms a cavity as a molding space for a package, a transfer pot as a resin loading space, and a plunger that communicates with the transfer pot to force resin out of the pot and into the cavity;

placing a lead frame having a semiconductor element mounted thereon between the top-half mold and the bottom-half mold within the cavity;

introducing resin into the cavity using the plunger; and

reducing a pressure in the cavity using a pressure adjuster to extract air from the cavity when a specified amount of resin has been introduced to the cavity, to form a semiconductor device package.

Claim 31 (New): The method of manufacturing semiconductor device packages of claim 30, wherein the specified amount of resin is an amount of resin that fills about one half of the cavity.

Claim 32 (New): The method of manufacturing semiconductor device packages of claim 30, further comprising detecting a position of the plunger to determine when the specified amount of resin has been introduced to the cavity.

Claim 33 (New): The method for manufacturing semiconductor device packages of claim 30, further comprising detecting an amount of time the plunger is driven to determine when the specified amount of resin has been introduced to the cavity.

Claim 34 (New): The method of manufacturing semiconductor device packages of claim 30, wherein the specified amount of resin is an amount of resin that is supplied to the cavity without hardening.